Product Change Notification - JAON-06LEME647

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Date:

08 Aug 2018

Product Category:

32-bit Microcontrollers

Affected CPNs:

Notification subject:

CCB 3497 Initial Notice: Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0mm) package.

Notification text:

PCN Status:
Initial notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0mm) package.

Pre Change:
Assembled at ANAP using AuPd or PdCu wire, 3230 die attach, G700 mold compound and C194 leadframe material or assembled at ASE using PdCu or CuPdAu wire, CRM-1076WA die attach, EME-G631H mold compound and C7025 leadframe material.

Post Change:
Assembled at ANAP using AuPd or PdCu wire, 3230 die attach, G700 mold compound and C194 leadframe material or assembled at ASE using PdCu or CuPdAu wire, CRM-1076WA die attach, EME-G631H mold compound and C7025 leadframe material or assembled at MMT using Au wire, 3280 die attach, G700 mold compound and C7025 leadframe material.

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	ASE Inc. Taiwan (ASE)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	ASE Inc. Taiwan (ASE)	Microchip Technology Thailand Branch (MMT)
Wire material	AuPd/PdCu	PdCu/CuPdAu	AuPd/PdCu	PdCu/CuPdAu	Au
Die attach material	3230	CRM-1076WA	3230	CRM-1076WA	3280
Molding compound material	G700	EME-G631H	G700	EME-G631H	G700
Lead frame material	C194	C7025	C194	C7025	C7025
MSL Classification	MSL 3	MSL 3	MSL 3	MSL 3	MSL 1 or MSL 2

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve on-time delivery performance by qualifying MMT as an additional new assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
November 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2018					-->	**November 2018**			
Workweek	31	32	33	34	35		45	46	47	48
Initial PCN Issue Date		X								

Qual Report Availability								X		
Final PCN Issue Date								X		

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
August 8, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
PCN_JAON-06LEME647_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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